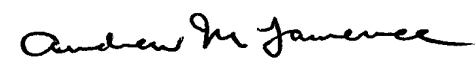




IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:	)	
	)	
Dong Ho Lee <i>et al.</i>	)	I hereby certify that this paper is being
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For: Method of Manufacturing a	)	this date:
Semiconductor Wafer	)	
	)	December 27, 2004
Group Art Unit: 2813	)	
	)	
Examiner: Chandra P. Chaudhari	)	Andrew M. Lawrence, Reg. No. 46,130
	)	Attorney for Applicants

AMENDMENT "A"

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This paper is in response to the official action dated August 25, 2004  
(hereafter, "the official action").

The **Amendments to the Specification** section begins on page 2 of this paper.

The **Complete Listing of Claims** begins on page 3 of this paper.

The **Remarks** section begins on page 4 of this paper.